Title (en)

Arrangement for removing thermal loads.

Title (de)

Anordnung zum Abführen von Wärmelasten.

Title (fr)

Structure pour évacuer des charges thermiques.

Publication

EP 0508176 B1 19950517 (DE)

Application

EP 92104769 A 19920319

Priority

- DE 4111896 A 19910412
- DE 4134712 A 19911021

Abstract (en)

[origin: EP0508176A2] In order to develop an arrangement for removing thermal loads from a room via cooling surfaces, in particular via suspended ceilings (6), formed essentially from air-impermeable elements (5.2; 7.2), and/or fore-positioned wall shells (8), both with a cavity (3; 3'), having at least one cooling device (10; 20), to the surrounding walls (1.1; 1.2) of the room, it being possible to reduce the surface temperature of the elements (5.2; 7.2) by means of the cavity air via the cooling device (10; 20), which can be connected to a cold source, for reducing the heat content of the cavity air, in such a manner that the elements (5.2; 7.2) need no connections to a circuit of a cooling liquid and that, in particular, with simple construction, good adaptability to internal architectonic conditions is guaranteed and the comfort limits can be observed in operation, a cooling device (10; 20) is arranged in the cavity (3; 3') between bare ceiling (1.1) and suspended finished ceiling (6), held by a support structure, or between bare wall (1.2) and fore-positioned wall shell (8) of a building, which cooling device has a heat exchanger (14; 22), and the air situated in the ceiling cavity or wall cavity (3; 3') is circulated in the circuit as heat transfer medium and on each circulation is cooled on the heat exchanger (14; 22) of the cooling device (10; 20). <IMAGE>

IPC 1-7

F24F 5/00

IPC 8 full level

F24F 5/00 (2006.01)

CPC (source: EP)

F24F 5/0089 (2013.01); F24F 5/0092 (2013.01)

Cited by

EP0663571A3; EP0740114A3; EP0849545A3; DE102016125735A1; EP1072846A3; FR3129712A1; WO2023099555A1

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